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PATENT #71A 9J

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: **Kasuhiro ANDO et al.**

Serial No.: **Not Yet Assigned**
(PCT/JP00/00645)

Filed: **August 1, 2001**

For: **CURABLE RESIN COMPOSITION**

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

August 1, 2001

Sir:

Prior to the calculation of the filing fees of the above application, please amend the application as follows:

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 13, line 8, with the following rewritten paragraph:

--As the (I) component, a modification product derived from the reactive silicon group-

A1 containing polyoxyalkylene polymer can also be employed. As a representative example of such modification product, there can be mentioned the polymer obtainable by polymerizing a mixture of

*SUB
B5* an alkyl (meth) acrylate monomer having an alkyl group containing 1 to 8 carbon atoms as represented by the following general formula (9) and/or an alkyl (meth) acrylate monomer having an alkyl group containing 10 or more carbon atoms as represented by the following general formula (10) and/or a reactive silicon group-containing alkyl (meth) acrylate monomer of the following